

L Number	Hits	Search Text	DB	Time stamp
1	4583	(remov\$3 or strip\$4 or etch\$3) with (porous near2 (film\$1 or layer\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/06 15:07
8	787	((remov\$3 or strip\$4 or etch\$3) with (porous near2 (film\$1 or layer\$1))) and (134/\$7.ccls. or 216/\$7.ccls. or 156/\$7.ccls. or 438/\$7.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/06 15:15
15	217	(((remov\$3 or strip\$4 or etch\$3) with (porous near2 (film\$1 or layer\$1))) and (134/\$7.ccls. or 216/\$7.ccls. or 156/\$7.ccls. or 438/\$7.ccls.)) and ((dip\$4 or immers\$3 or submerg\$3 or submers\$3) with (substrate\$1 or wafer\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/06 15:50
38	52	(((remov\$3 or strip\$4 or etch\$3) with (porous near2 (film\$1 or layer\$1))) and (134/\$7.ccls. or 216/\$7.ccls. or 156/\$7.ccls. or 438/\$7.ccls.)) and ((dip\$4 or immers\$3 or submerg\$3 or submers\$3) with (substrate\$1 or wafer\$1))) and (rotat\$3 same (substrate\$1 or wafer\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/06 15:56
52	494	((remov\$3 or strip\$4 or etch\$3) with (porous near2 (film\$1 or layer\$1))) and ((dip\$4 or immers\$3 or submerg\$3 or submers\$3) with (substrate\$1 or wafer\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/06 15:57
59	86	(((remov\$3 or strip\$4 or etch\$3) with (porous near2 (film\$1 or layer\$1))) and ((dip\$4 or immers\$3 or submerg\$3 or submers\$3) with (substrate\$1 or wafer\$1))) and (rotat\$3 same (substrate\$1 or wafer\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/06 15:56
66	34	(((remov\$3 or strip\$4 or etch\$3) with (porous near2 (film\$1 or layer\$1))) and ((dip\$4 or immers\$3 or submerg\$3 or submers\$3) with (substrate\$1 or wafer\$1))) and (rotat\$3 same (substrate\$1 or wafer\$1))) not ((((remov\$3 or strip\$4 or etch\$3) with (porous near2 (film\$1 or layer\$1))) and (134/\$7.ccls. or 216/\$7.ccls. or 156/\$7.ccls. or 438/\$7.ccls.)) and ((dip\$4 or immers\$3 or submerg\$3 or submers\$3) with (substrate\$1 or wafer\$1))) and (rotat\$3 same (substrate\$1 or wafer\$1)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/06 15:57